

### **LISTING OF THE CLAIMS:**

1. (Currently Amended) An intermediate base for a module having at least one semiconductor component, said base comprising a flat base body having an upper face on which internal connections are formed for connection to connecting elements of a semiconductor component, a lower face which is provided with external connections for making contact with a circuit carrier, said base body being a film composed of plastic material whose coefficient of expansion is approximately the same as the coefficient of expansion of the semiconductor component and having through-holes between the upper face and the lower face, said through-holes having walls of said plastic material being ~~which are~~ at least partially metallized to make a conductive connection between ~~an~~ each internal connection on the upper face and a corresponding external connection on the lower face, the walls of the through-holes being at least partially exposed in the region of the lower face of the base body by means of annular notches which are incorporated adjacent to a circumferential edge of the through-holes to form freestanding studs as external connections, said studs having an outer rim in the plane of the lower face.

2. (Previously Presented) The intermediate base according to claim 1, wherein annular notches are concentric to form tubular studs.

3. (Previously Presented) The intermediate base according to claim 1, wherein at least one of the notches is eccentric so that the stud associated therewith is approximately in the form of a tubular segment.

Claim 4 (cancelled).

5. (Currently Amended) The intermediate base according to ~~claim 4~~ claim 1, wherein the film is composed of liquid crystal polymer.

6. (Currently Amended) The intermediate base according to claim 1, wherein the external connections are in the form of metal layers on ~~an~~ the outer rim of the studs.

7. (Previously Presented) The intermediate base according to claim 6, wherein the external connecting elements have an additional solder layer.

8. (Previously Presented) The intermediate base according to claim 6, wherein the through-holes are at least partially filled with a solder material.

Claim 9 (cancelled).

10. (Currently Amended) A semiconductor module comprising a semiconductor chip and an intermediate base, said intermediate base having a flat base body of a plastic material having an upper face on which internal connections are formed for connection to connecting elements of the semiconductor chip, the semiconductor chip being secured on the upper face with the connecting elements directly engaging the internal connections, said flat base body having a lower face which is provided with external connections for making contact with a circuit carrier, and through-holes extending between the upper face and the lower face, each of said through-holes having ~~walls~~ a wall of the plastic material which wall is ~~are~~ at least partially metallized for making a conductive connection between an internal connection on the upper face and a corresponding external connection on the lower face, the ~~walls~~ wall of each of the through-holes being at least partially exposed in the region of the lower face of the base body by means of annular notches which are incorporated adjacent a circumferential edge of the through-hole to form a freestanding stud as an external connection.

Claims 11-15 (cancelled).

16. (Currently Amended) A semiconductor module comprising a semiconductor component and an intermediate base, said intermediate base having a flat base body in the form of a film composed of a plastic material having a coefficient of expansion approximately the same as a coefficient expansion of the semiconductor component, said base body having an upper face on which internal connections are formed for connection to connecting elements of the semiconductor component, the semiconductor component being connected directly with the upper face of the base body so that the connecting elements rest directly on the internal connections, said flat base body having a lower face which is provided with external connections for making contact with a circuit carrier, said base body having through-holes extending in each case directly between one of the internal connections on the upper face and an external connection on the lower face, each of said through-holes having

walls a wall which ~~are~~ is at least partially metallized for making a conductive connection between an internal connection on the upper face and a corresponding external connection on the lower face and the walls wall of each of the through-holes being at least partially exposed in the region of the lower face of the base body by means of annular notches which are incorporated adjacent a circumferential edge of the through-hole to form a free-standing stud as ~~an~~ the external connection.

17. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein the base body is connected to the semiconductor component via an adhesive layer.

18. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein the annular notches are concentric to form tubular studs.

19. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein at least one of the notches is eccentric so that the stud associated therewith is approximately in the form of a tubular segment.

20. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein the film is composed of a liquid crystal polymer.

21. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein the external connections are in the form of metal layers on an outer rim of the studs.

22. (Currently Amended) ~~A~~ The semiconductor module according to claim 21, wherein the external connections have an additional solder layer.

23. (Currently Amended) ~~A~~ The semiconductor module according to claim 16, wherein the through-holes are at least partially filled with a solder material.

Claim 24 (cancelled).

25. (New) The semiconductor module according to claim 16, wherein the connecting elements of the semiconductor component are metal pads which are contacted by the internal connection, which is a metal film layer of the metallized through-hole.

26. (New) The intermediate base according to claim 1, wherein the internal connection is a portion of a metal layer of the metallized through-hole.

27. (New) The semiconductor module according to claim 10, wherein the semiconductor chip is secured on the upper face by a thin layer of adhesive material.